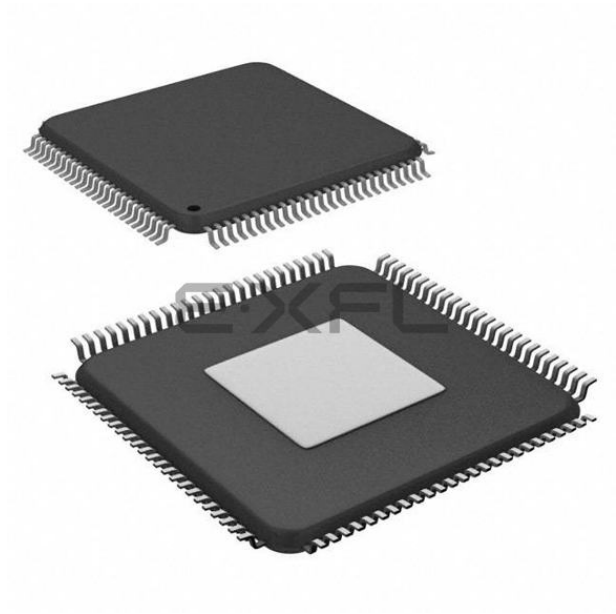

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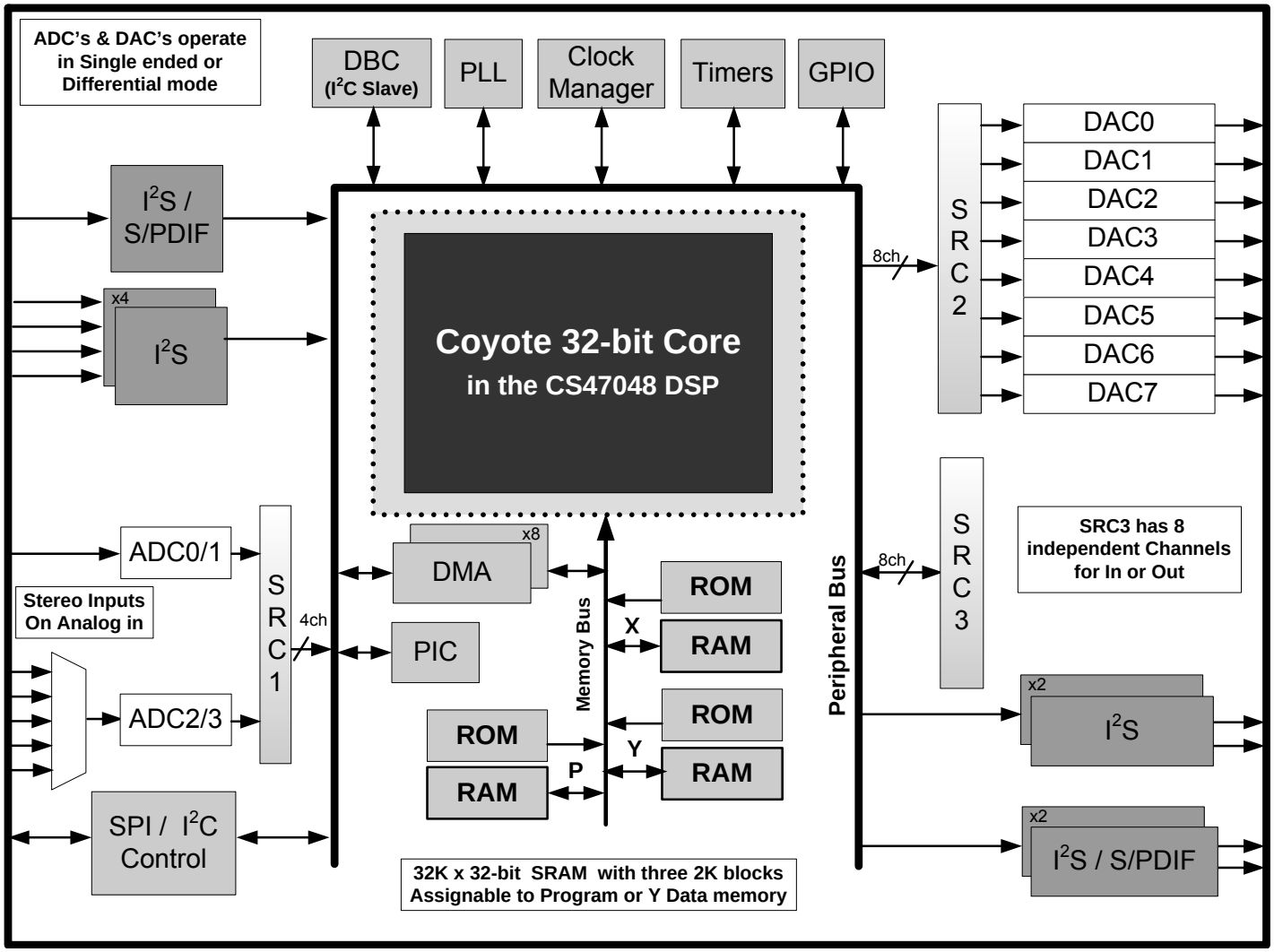
Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Fixed Point
Interface	I²C, SPI
Clock Rate	150MHz
Non-Volatile Memory	-
On-Chip RAM	128kB
Voltage - I/O	3.30V
Voltage - Core	1.80V
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	100-LQFP-EP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/cirrus-logic/cs47048c-dqz



CS47048 Block Diagram

Contacting Cirrus Logic Support

For all product questions and inquiries, contact a Cirrus Logic Sales Representative.
To find the one nearest you, go to www.cirrus.com.

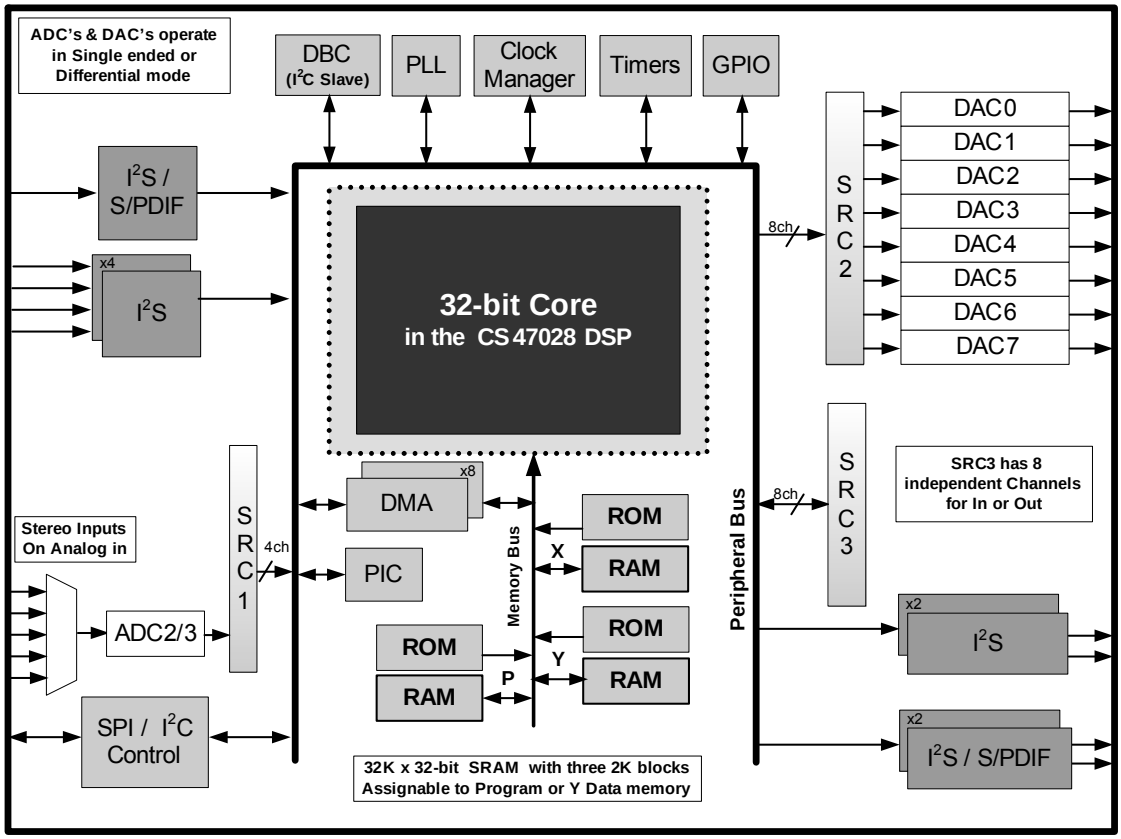


Figure 4-2. CS47028 Top-level Block Diagram

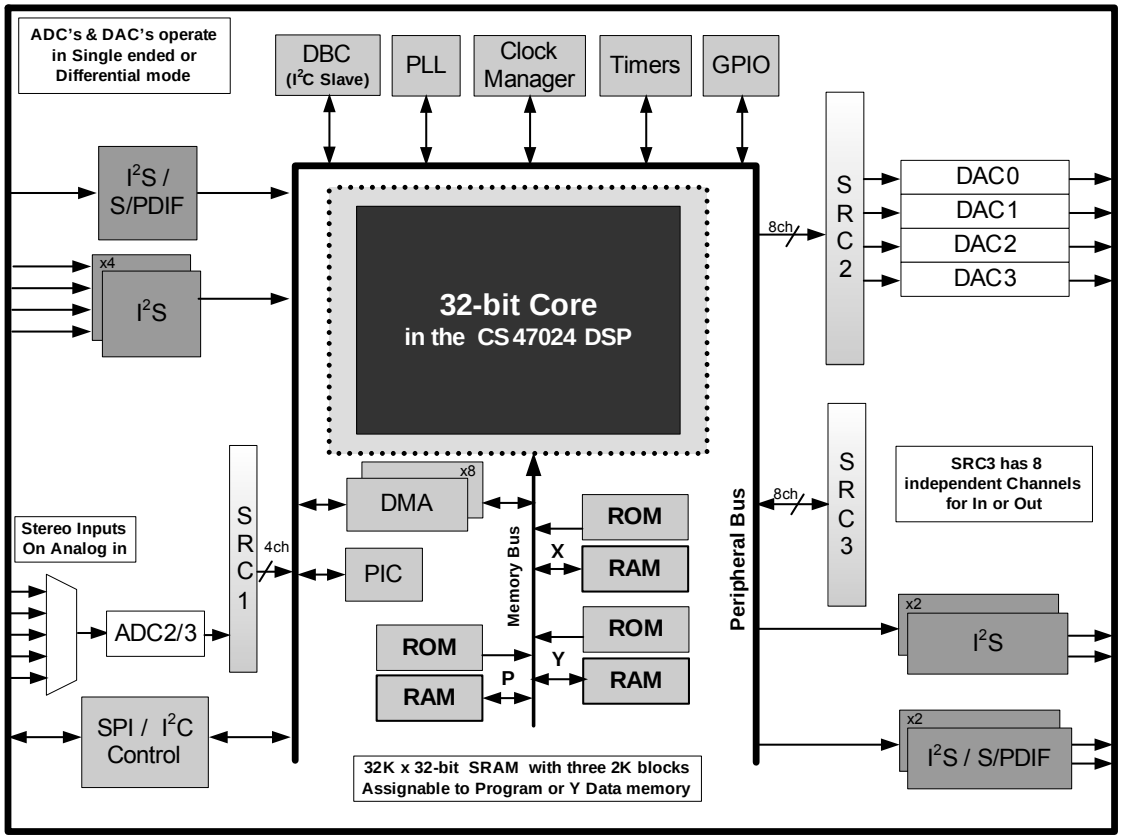


Figure 4-3. CS47024 Top-level Block Diagram

4.3.2 Digital to Analog Converter Port (DAC)

The DACs in the CS470xx devices feature dynamic range performance in excess of 100 dB. See Section 5.17 for more details on CS470xx DAC performance. The CS47024 device supports four simultaneous channels of digital-to-analog conversion. The CS47028 and CS47048 devices provide eight simultaneous channels of digital-to-analog conversion. The DACs have voltage mode outputs that can be connected either as single-ended or differential signals. The conversions are performed with Fs=96 kHz.

4.3.3 Digital Audio Input Port (DAI)

The input capabilities for each version of the CS470xx are summarized in Table 3-1 and Table 3-2.

Up to five DAI ports are available. Two of the DAI ports can be programmed to implement other functions. If the SPI mode is used, the DAI_DATA4 pin becomes the SCP_CS input. The integrated S/PDIF receiver can be used to take over the DAI_DATA3 pin.

The DAI port PCM inputs have a single slave-only clock domain. The S/PDIF receiver, if used, is a separate clock domain. The output of the S/PDIF Rx can then be converted through one of the internal SRC blocks to synchronize with the PCM input. The sample rate of the input clock domains can be determined automatically by the DSP, off-loading the task of monitoring the S/PDIF Rx from the host. A time-stamping feature provides the ability to also sample-rate convert the input data via software.The DAI port supports PCM format with word lengths up to 32 bits and sample rates as high as 192 kHz.

The DAI also supports a time division multiplexed (TDM) mode that packs up to 10 PCM audio channels on a single data line.

4.3.4 S/PDIF RX Input Port (DAI)

One of the PCM pins of the DAI can also be used as a DC-coupled, TTL-level S/PDIF Rx input capable of receiving and demodulating bi-phase encoded S/PDIF signals with Fs $\leq$ 192 kHz.

4.3.5 Digital Audio Output Port (DAO)

DAO port supports PCM resolutions of up to 32-bits. The port supports sample rates (Fs) as high as 192 kHz. The port can be configured as an independent clock domain mastered by the DSP, or as a clock slave if an external MCLK or SCLK/LRCLK source is available.

The DAO also supports a time division multiplexed (TDM) mode, that packs up to 8 channels of PCM audio on a single data line.

4.3.6 S/PDIF TX Output Port (DAO)

Two of the serial audio pins can be re-configured as S/PDIF TX pins that drive a bi-phase encoded S/PDIF signal (data with embedded clock on a single line).

4.3.7 Sample Rate Converters (SRC)

All CS470xx devices have at least two internal hardware SRC modules. One is directly associated with the ADCs and normally serves to convert data from the 96 kHz sampling rate of the ADCs to another Fs appropriate for mixing with other audio in the system.

The other SRC module is directly associated with the DACs and normally serves to convert data from the DSP into the 96 kHz sample rate needed by the DACs.

The CS47024, CS47028, and CS47048 devices have an additional stand-alone 8-channel SRC module. This SRC module can be used to make independent input clock domains synchronous (different Fs on PCM input and S/PDIF Rx).

5 Characteristics and Specifications

Note: All data sheet minimum and maximum timing parameters are guaranteed over the rated voltage and temperature. All data sheet typical parameters are measured under the following conditions: T = 25°C, VDD = 1.8 V, VDDIO = VDDA = 3.3 V, GND = GNDIO = GNDA = 0 V.

5.1 Absolute Maximum Ratings

(GND = GNDIO = GNDA = 0V; all voltages with respect to 0V)

Parameter	Symbol	Min	Max	Unit
DC power supplies: Core supply Analog supply I/O supply |VDDA–VDDIO|	 VDD VDDA VDDIO	 –0.3 –0.3 –0.3 —	 2.0 3.6 3.6 0.3	 V V V V
Input pin current, any pin except supplies	I_{in}	—	±10	mA
Input voltage on PLL_REF_RES	V_{filt}	–0.3	3.6	V
Input voltage on digital I/O pins	V_{inio}	–0.3	5.0	V
Analog Input Voltage	V_{in}	AGND–0.7	VA+0.7	V
Storage temperature	T_{stg}	–65	150	°C

WARNING: Operation at or beyond these limits can result in permanent damage to the device. Normal operation is not guaranteed at these extremes.

5.2 Recommended Operating Conditions

(GND = GNDIO = GNDA = 0V; all voltages with respect to 0V)

Parameter	Symbol	Min	Typ	Max	Unit
DC power supplies: Core supply Analog supply I/O supply |VDDA – VDDIO|	 VDD VDDA VDDIO	 1.71 3.13 3.13	 1.8 3.3 3.3 0	 1.89 3.46 3.46	 V V V V
Ambient operating temperature Commercial—CQZ (147 MHz) Automotive—DQZ (131 MHz) Automotive—DQZ (113 MHz)	T_A	 0 –40 –40	—	 +70 +85 +105	°C

Note: It is recommended that the 3.3 V IO supply come up ahead of or simultaneously with the 1.8 V core supply.

5.3 Digital DC Characteristics

(Measurements performed under static conditions.)

Parameter	Symbol	Min	Typ	Max	Unit
High-level input voltage	V_{IH}	2.0	—	—	V
Low-level input voltage, except XTI	V_{IL}	—	—	0.8	V
Low-level input voltage, XTI	V_{ILKXTI}	—	—	0.6	V
Input Hysteresis	V_{hys}	—	0.4	—	V
High-level output voltage (I_O = –2mA), except XTO	V_{OH}	VDDIO*0.9	—	—	V
Low-level output voltage (I_O = 2mA), except XTO	V_{OL}	—	—	VDDIO*0.1	V
Input leakage XTI	I_{LXTI}	—	—	5	µA
Input leakage current (all digital pins with internal pull-up resistors enabled)	I_{LEAK}	—	—	70	µA

5.4 Power Supply Characteristics

Note: Measurements performed under operating conditions

Parameter	Min	Typ	Max	Unit
Operational Power Supply Current:				
VDD: Core and I/O operating[1]	—	325	—	mA
VDDA: PLL operating current	—	16	—	mA
VDDA: DAC operating current (all 8 channels enabled)	—	56	—	mA
VDDA: ADC operating current (all 4 channels enabled)	—	34	—	mA
VDDIO: With most ports operating	—	27	—	mA
Total Operational Power Dissipation:		1025		mW
Standby Power Supply Current:				
VDD: Core and I/O not clocked	—	410	—	µA
VDDA: PLLs halted	—	26	—	µA
VDDA: DAC disabled	—	40	—	µA
VDDA: ADC disabled	—	24	—	µA
VDDIO: All connected I/O pins 3-stated by other ICs in system	—	215	—	µA
Total Standby Power Dissipation:		1745		µW

1. Dependent on application firmware and DSP clock speed.

5.5 Thermal Data (100-pin LQFP with Exposed Pad)

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance (Junction to Ambient) Two-layer Board[1] Four-layer Board[2]	θ_{ja}	 — —	 34 18	 — —	°C/Watt
Thermal Resistance (Junction to Top of Package) Two-layer Board[1] Four-layer Board[2]	ψ_{jt}	 — —	 0.54 .28	 — —	°C/Watt

1. To calculate the die temperature for a given power dissipation:
   T_j = Ambient temperature + [(Power Dissipation in Watts) * θ_{ja}]
2. To calculate the case temperature for a given power dissipation:
   $T_c = T_j$ - [(Power Dissipation in Watts) * ψ_{jt}]

Note: Two-layer board is specified as a 76 mm X 114 mm, 1.6 mm thick FR-4 material with 1-oz. copper covering 20% of the top and bottom layers.

Four-layer board is specified as a 76 mm X 114 mm, 1.6 mm thick FR-4 material with 1-oz. copper covering 20% of the top and bottom layers and 0.5-oz. copper covering 90% of the internal power plane and ground plane layers.

5.6 Digital Switching Characteristics–RESET

Parameter	Symbol	Min	Max	Unit
$\overline{\text{RESET}}$ minimum pulse width low[1]	T_{rstl}	1	—	µs
All bidirectional pins high-Z after $\overline{\text{RESET}}$ low	T_{rst2z}	—	200	ns
Configuration pins setup before $\overline{\text{RESET}}$ high	T_{rstsu}	50	—	ns
Configuration pins hold after $\overline{\text{RESET}}$ high	T_{rsthld}	20	—	ns

1. The rising edge of $\overline{\text{RESET}}$ must not occur before the power supplies are stable at the recommended operating values as described in Section 5.2. In addition, for the configuration pins to be read correctly, the $\overline{\text{RESET}}$ T_{rstl} requirement must be met.

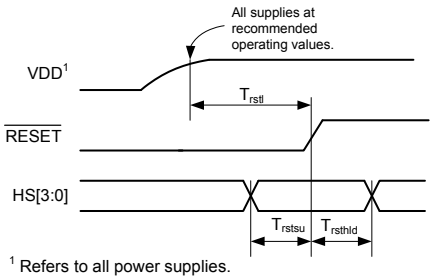


Figure 5-1. $\overline{\text{RESET}}$ Timing at Power-on

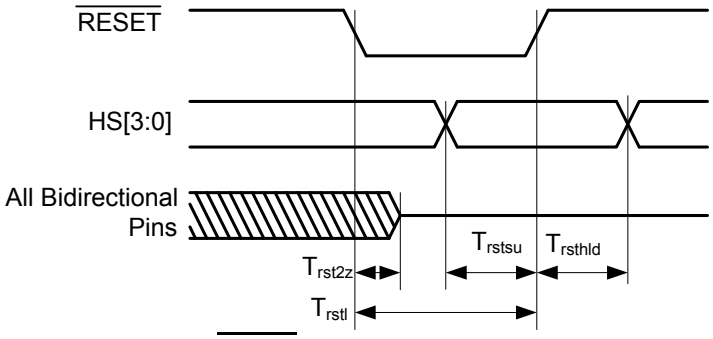


Figure 5-2. $\overline{\text{RESET}}$ Timing after Power is Stable

5.7 Digital Switching Characteristics–XTI

Parameter	Symbol	Min	Max	Unit
External Crystal operating frequency[1]	F_{xtal}	12.288	24.576	MHz
XTI period	T_{clki}	41	81	ns
XTI high time	T_{clkih}	13.3	—	ns
XTI low time	T_{clkil}	13.3	—	ns
External Crystal Load Capacitance (parallel resonant)[2]	C_L	10	18	pF
External Crystal Equivalent Series Resistance	ESR	—	50	Ω

1. Part characterized with the following crystal frequency values: 12.288 and 24.576 MHz.
2. C_L refers to the total load capacitance as specified by the crystal manufacturer. Crystals that require a C_L outside this range should be avoided. The crystal oscillator circuit design should follow the crystal manufacturer's recommendation for load capacitor selection.

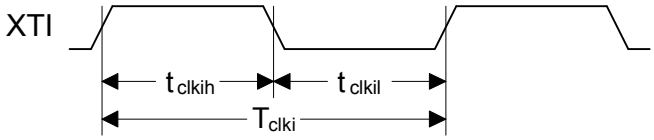


Figure 5-3. XTI Timing

5.8 Digital Switching Characteristics–Internal Clock

Parameter	Symbol	Min (2-layer Boards)	Min (4-layer Boards)	Max (2-layer Boards)	Max (4-layer Boards)	Unit
Internal DSP_CLK frequency[1]	F_{dclk}	(See Footnote 2)				MHz
CS47048-CQZ		F_{xtal}		147	147	
CS47048-DQZ		F_{xtal}		131	147	
CS47028-CQZ		F_{xtal}		147	147	
CS47028-DQZ		F_{xtal}		131	147	
CS47024-CQZ		F_{xtal}		147	147	
CS47024-DQZ		F_{xtal}		131	147	
Internal DSP_CLK period[1]	DCLKP					ns
CS47048-CQZ		6.8	6.8	$1/F_{xtal}$		
CS47048-DQZ		7.6	6.8	$1/F_{xtal}$		
CS47028-CQZ		6.8	6.8	$1/F_{xtal}$		
CS47028-DQZ		7.6	6.8	$1/F_{xtal}$		
CS47024-CQZ		6.8	6.8	$1/F_{xtal}$		
CS47024-DQZ		7.6	6.8	$1/F_{xtal}$		

1. After initial power-on reset, $F_{dclk} = F_{xtal}$. After initial kick-start commands, the PLL is locked to max F_{dclk} and remains locked until the next power-on reset.
2. See Section 5.7. for all references to F_{xtal}.

5.9 Digital Switching Characteristics–Serial Control Port–SPI Slave Mode

Parameter	Symbol	Min	Typical	Max	Unit
SCP_CLK frequency[1]	f_{spisck}	—	—	25	MHz
$\overline{\text{SCP\_CS}}$ falling to SCP_CLK rising	t_{spicss}	24	—	—	ns
SCP_CLK low time	t_{spickl}	20	—	—	ns
SCP_CLK high time	t_{spickh}	20	—	—	ns
Setup time SCP_MOSI input	t_{spidsu}	5	—	—	ns
Hold time SCP_MOSI input	t_{spidh}	5	—	—	ns
SCP_CLK low to SCP_MISO output valid	t_{spidov}	—	—	11	ns
SCP_CLK falling to $\overline{\text{SCP\_IRQ}}$ rising	$t_{spiirqh}$	—	—	27	ns
$\overline{\text{SCP\_CS}}$ rising to $\overline{\text{SCP\_IRQ}}$ falling	$t_{spiirql}$	0	—	—	ns
SCP_CLK low to $\overline{\text{SCP\_CS}}$ rising	t_{spicsh}	24	—	—	ns
$\overline{\text{SCP\_CS}}$ rising to SCP_MISO output high-Z	$t_{spicsdz}$	—	20	—	ns
SCP_CLK rising to $\overline{\text{SCP\_BSY}}$ falling	$t_{spicbsyl}$	—	3*DCLKP+20	—	ns

1. f_{spisck} indicates the maximum speed of the hardware. The system designer should be aware that the actual maximum speed of the communication port can be limited by the firmware application. Flow control using the $\overline{\text{SCP\_BSY}}$ pin should be implemented to prevent overflow of the input data buffer. At boot the maximum speed is $F_{xtal}/3$.

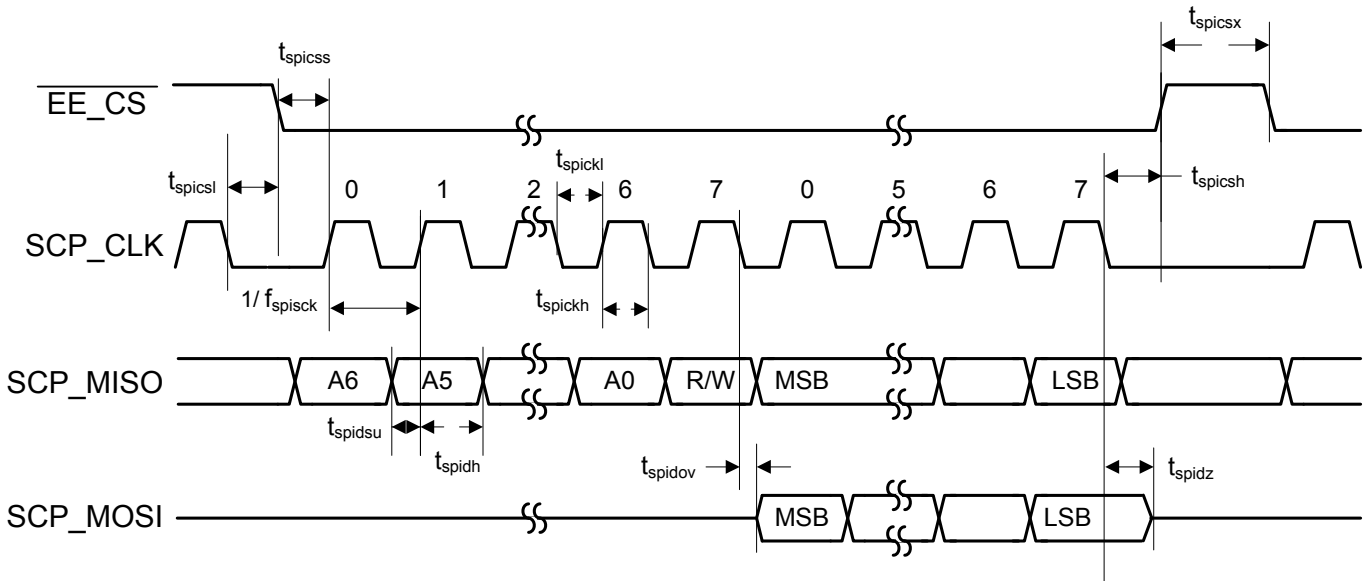


Figure 5-5. Serial Control Port–SPI Master Mode Timing

5.11 Digital Switching Characteristics–Serial Control Port I2C Slave Mode

Parameter	Symbol	Min	Typical	Max	Units
SCP_CLK frequency[1]	f_{iicck}	—	—	400	kHz
SCP_CLK rise time	t_{iicr}	—	—	150	ns
SCP_CLK fall time	t_{iicf}	—	—	150	ns
SCP_CLK low time	t_{iicckl}	1.25	—	—	µs
SCP_CLK high time	t_{iicckh}	1.25	—	—	µs
SCP_CLK rising to SCP_SDA rising or falling for START or STOP condition	$t_{iicckcmd}$	1.25	—	—	µs
START condition to SCP_CLK falling	$t_{iicstscl}$	1.25	—	—	µs
SCP_CLK falling to STOP condition	t_{iicstp}	2.5	—	—	µs
Bus free time between STOP and START conditions	t_{iicbft}	3	—	—	µs
Setup time SCP_SDA input valid to SCP_CLK rising	t_{iicsu}	110	—	—	ns
Hold time SCP_SDA input after SCP_CLK falling	t_{iich}	100	—	—	ns
SCP_CLK low to SCP_SDA out valid	t_{iicdov}	—	—	18	ns
SCP_CLK falling to $\overline{\text{SCP\_IRQ}}$ rising	$t_{iicirqh}$	—	—	3*DCLKP+40	ns
NAK condition to $\overline{\text{SCP\_IRQ}}$ low	$t_{iicirql}$	—	3*DCLKP+20	—	ns
SCP_CLK rising to $\overline{\text{SCB\_BSY}}$ low	$t_{iicbsyl}$	—	3*DCLKP+20	—	ns

1. f_{iicck} indicates the maximum speed of the hardware. The system designer should be aware that the actual maximum speed of the communication port can be limited by the firmware application. Flow control using the $\overline{\text{SCP\_BSY}}$ pin should be implemented to prevent overflow of the input data buffer.

I2C Slave Address = 0x82

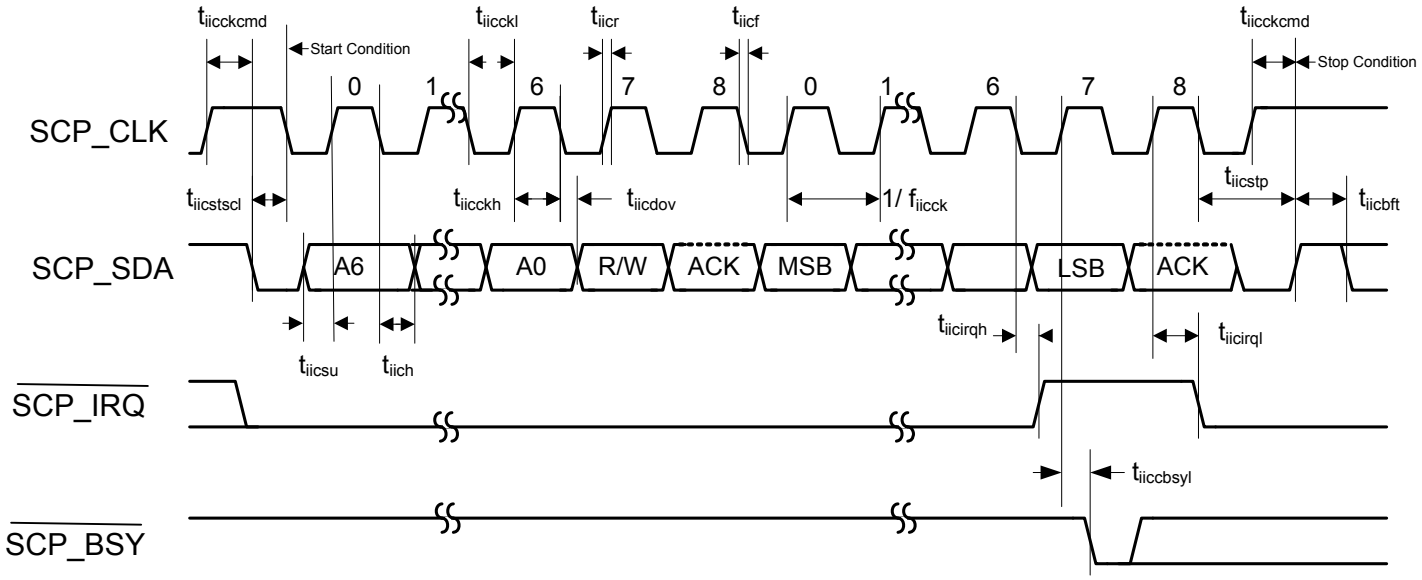


Figure 5-6. Serial Control Port–I2C Slave Mode Timing

5.12 Digital Switching Characteristics–Serial Control Port–I2C Master Mode

Parameter	Symbol	Min	Max	Units
SCP_CLK frequency[1]	f_{iicck}	—	400	kHz
SCP_CLK rise time	t_{iicr}	—	150	ns
SCP_CLK fall time	t_{iicf}	—	150	ns
SCP_CLK low time	t_{iicckl}	1.25	—	µs
SCP_CLK high time	t_{iicckh}	1.25	—	µs
SCP_CLK rising to SCP_SDA rising or falling for START or STOP condition	$t_{iicckcmd}$	1.25	—	µs
START condition to SCP_CLK falling	$t_{iicstscl}$	1.25	—	µs
SCP_CLK falling to STOP condition	t_{iicstp}	2.5	—	µs
Bus free time between STOP and START conditions	t_{iicbft}	3	—	µs
Setup time SCP_SDA input valid to SCP_CLK rising	t_{iicsu}	110	—	ns
Hold time SCP_SDA input after SCP_CLK falling	t_{iich}	100	—	ns
SCP_CLK low to SCP_SDA out valid	t_{iicdov}	—	36	ns

1. f_{iicck} indicates the maximum speed of the hardware. The system designer should be aware that the actual maximum speed of the communication port can be limited by the firmware application.

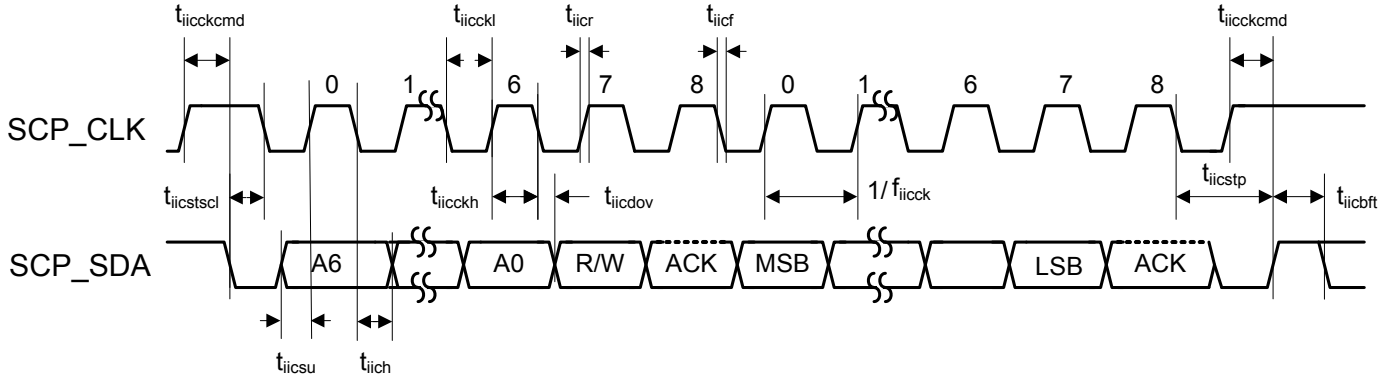


Figure 5-7. Serial Control Port–I2C Master Mode Timing

5.13 Digital Switching Characteristics–Digital Audio Slave Input Port

Parameter	Symbol	Min	Max	Unit
DAI_SCLK period	$T_{daiclkp}$	20	—	ns
DAI_SCLK duty cycle	—	45	55	%
Setup time DAI_DATAn	t_{daidsu}	8	—	ns
Hold time DAI_DATAn	t_{daidh}	5	—	ns

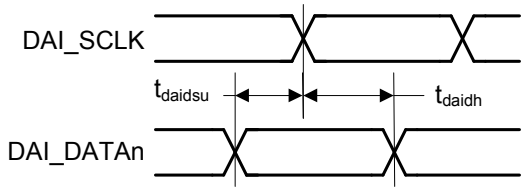


Figure 5-8. Digital Audio Input (DAI) Port Timing Diagram

5.14 Digital Switching Characteristics–Digital Audio Output Port

Parameter	Symbol	Min	Max	Unit
DAO_MCLK period	$T_{daomclk}$	20	—	ns
DAO_MCLK duty cycle	—	45	55	%
DAO_SCLK period for Master or Slave mode[1]	$T_{daosclk}$	20	—	ns
DAO_SCLK duty cycle for Master or Slave mode[1]	—	40	60	%
Master Mode (Output A1 Mode)[1,2]				
DAO_SCLK delay from DAO_MCLK rising edge, DAO MCLK as an input	$t_{daomsck}$	—	19	ns
DAO_LRCLK to DAO_SCLK inactive edge[3]. See Fig. 5-9.	$t_{daomlrts}$	—	8	ns
DAO_SCLK inactive edge[3] to DAO_LRCLK. See Fig. 5-10.	$t_{daomstlr}$	—	8	ns
DAO_DATA[3:0] delay from DAO_SCLK inactive edge[3]	t_{daomdy}	—	8	ns
Slave Mode (Output A0 Mode)[4]				
DAO_SCLK active edge to DAO_LRCLK transition. See Fig. 5-11.	$t_{daosstlr}$	10	—	ns
DAO_LRCLK transition to DAO_SCLK active edge. See Fig. 5-12.	$t_{daoslrts}$	10	—	ns
DAO_Dx delay from DAO_SCLK inactive edge	t_{daosdv}	—	11	ns

1. Master mode timing specifications are characterized, not production tested.
2. Master mode is defined as the CS47048 driving both DAO_SCLK, DAO_LRCLK. When MCLK is an input, it is divided to produce DAO_SCLK, DAO_LRCLK.
3. The DAO_LRCLK transition can occur on either side of the edge of DAO_SCLK. The active edge of DAO_SCLK is the point at which the data is valid.
4. Slave mode is defined as DAO_SCLK, DAO_LRCLK driven by an external source.

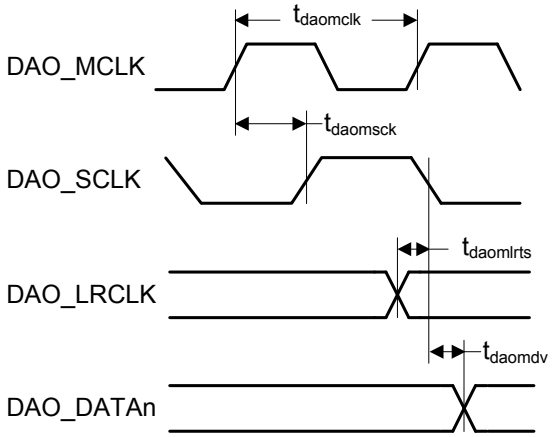


Figure 5-9. DAO_LRCLK Transition before DAO_SCLK Inactive Edge

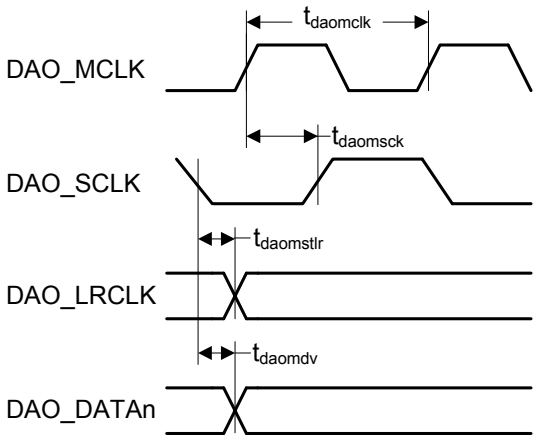


Figure 5-10. DAO_LRCLK Transition after DAO_SCLK Inactive Edge

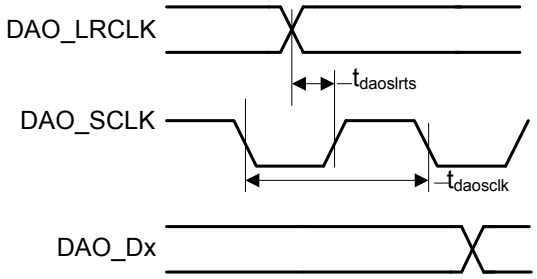


Figure 5-11. DAO_LRCLK Transition before DAO_SCLK Inactive Edge

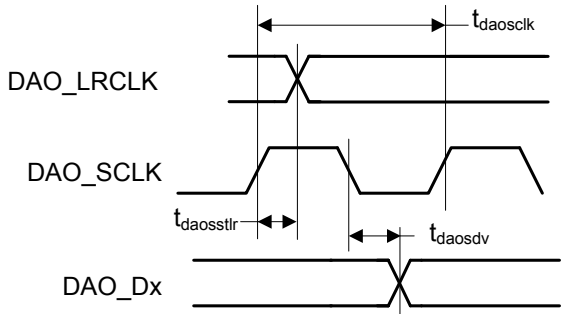


Figure 5-12. DAO_LRCLK Transition after DAO_SCLK Inactive Edge

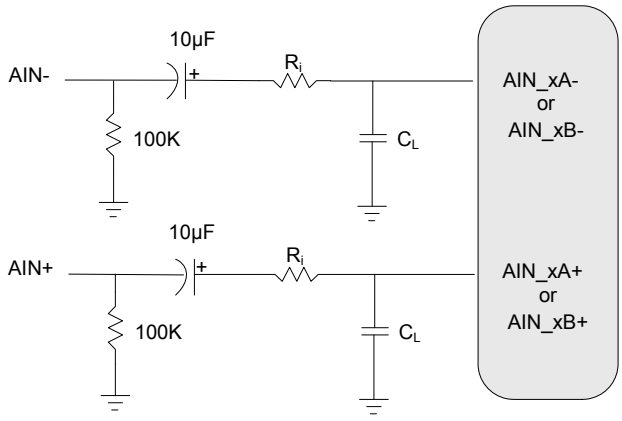


Figure 5-14. ADC Differential Input Test Circuit

5.16.3 ADC Digital Filter Characteristics

Parameter[1,2]	Min	Typ	Max	Unit
Fs = 96 kHz				
Passband (Frequency Response) to –0.1 dB corner	0	—	0.4896	Fs
Passband Ripple	—	—	0.08	dB
Stopband	0.5688	—	—	Fs
Stopband Attenuation	70	—	—	dB
Total Group Delay	—	12/Fs	—	s
High-pass Filter Characteristics				
Frequency Response: –3.0 dB –0.13 dB	 — —	 1 20	 — —	 Hz Hz
Phase Deviation @ 20 Hz	—	10	—	Deg
Passband Ripple	—	—	0	dB
Filter Settling Time	—	10^5/Fs	0	s

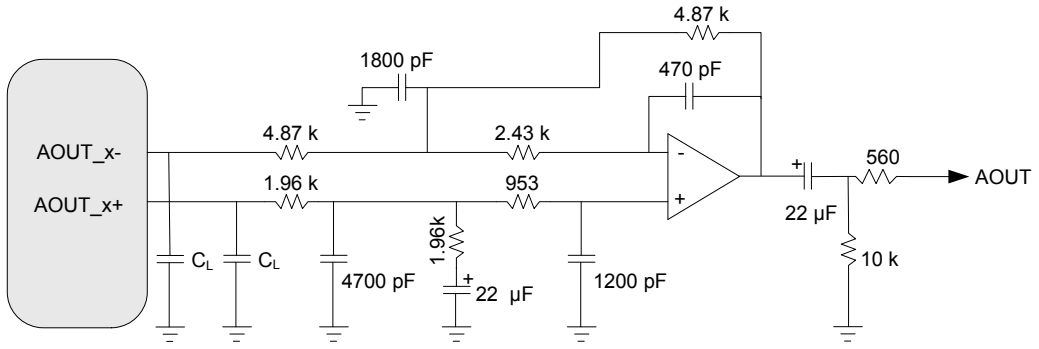
1. Filter response is guaranteed by design.
2. Response is clock-dependent and scales with Fs.

5.17 DAC Characteristics

5.17.1 Analog Output Characteristics (Commercial)

Test Conditions (unless otherwise specified): TA = 0–+70°C; VDD = 1.8V±5%, VDDA(VA) = 3.3V±5%; 1 kHz sine wave driven through a filter shown in Fig. 5-15 or Fig. 5-16; DSP running test application; Measurement Bandwidth is 20 Hz–20 kHz.

	Differential			Single-ended			
Parameter	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
Fs = 96 kHz							
Dynamic Range A-weighted Unweighted	 102 99	 108 105	 — —	 99 96	 105 102	 — —	 dB dB
Total Harmonic Distortion + Noise 0 dB –20 dB –60 dB	 — — —	 –98 –88 –48	 –90 — —	 — — —	 –95 –85 –45	 –87 — —	 dB dB dB
Interchannel Isolation (1 kHz)	—	95	—	—	95	—	dB



P output: $R_L = 1.96k + ([2\pi F*4700pF]^{-1} || (1.96k + [2\pi F*22\mu F^{-}]^{-1}) || (953 + [2\pi F*1200pF]^{-1}))$

N output: $R_L = 4.87k + ([2\pi F*1800pF]^{-1} || ((2.43k + [2\pi F*470pF]^{-1}) || 4.87k))$

Figure 5-16. DAC Differential Output Test Circuit

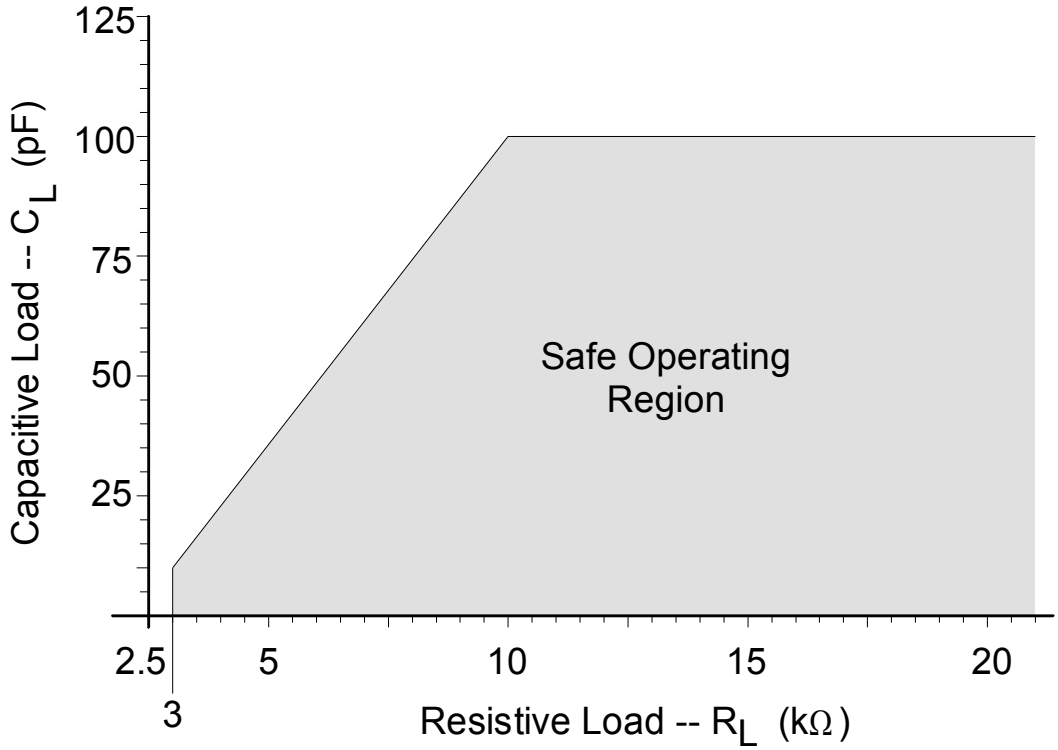


Figure 5-17. Maximum Loading

5.17.3 Combined DAC Interpolation and On-chip Analog Filter Response

Parameter	Min	Typ	Max	Unit
Passband (Frequency Response) to 0.22 dB corner to –3 dB corner	 0 0	 — —	 0.4125 0.4979	 Fs Fs
Frequency Response 10 Hz–20 kHz	–0.02	—	+0.02	dB
StopBand	0.5465	—	—	Fs
StopBand Attenuation	100	—	—	dB
Group Delay	—	10/Fs	—	s

6 Ordering Information

The CS470xx DSP part numbers are described as follows:

Example:
CS47048I-XYZR
where
I–ROM ID Letter
X–Product Grade
Y–Package Type
Z–Lead (Pb) Free
R–Tape and Reel Packaging

Table 6-1. Ordering Information

Part No.	Grade	Temp. Range	Package
CS47048C-CQZ	Commercial	0–+70°C	100-pin LQFP
CS47048C-DQZ	Automotive	–40–+85°C	
CS47048C-EQZ	Extended Automotive	–40–+105°C	
CS47028C-CQZ	Commercial	0–+70°C	
CS47028C-DQZ	Automotive	–40–+85°C	
CS47028C-EQZ	Extended Automotive	–40–+105°C	
CS47024C-CQZ	Commercial	0–+70°C	
CS47024C-DQZ	Automotive	–40–+85°C	
CS47024C-EQZ	Extended Automotive	–40–+105°C	

Note: Contact the factory for availability of the –D (automotive grade) package.

7 Environmental, Manufacturing, and Handling Information

Table 7-1. Environmental, Manufacturing, and Handling Information

Model Number	Peak Reflow Temp.	MSL[1] Rating	Max Floor Life
CS47048C-CQZ	260° C	3	7 days
CS47048C-DQZ			
CS47048C-EQZ			
CS47028C-CQZ	260° C	3	7 days
CS47028C-DQZ			
CS47028C-EQZ			
CS47024C-CQZ	260° C	3	7 days
CS47024C-DQZ			
CS47024C-EQZ			

1. Moisture Sensitivity Level as specified by IPC/JEDEC J-STD-020.

8 Device Pinout Diagrams

8.1 CS47048, 100-pin LQFP Pinout Diagram

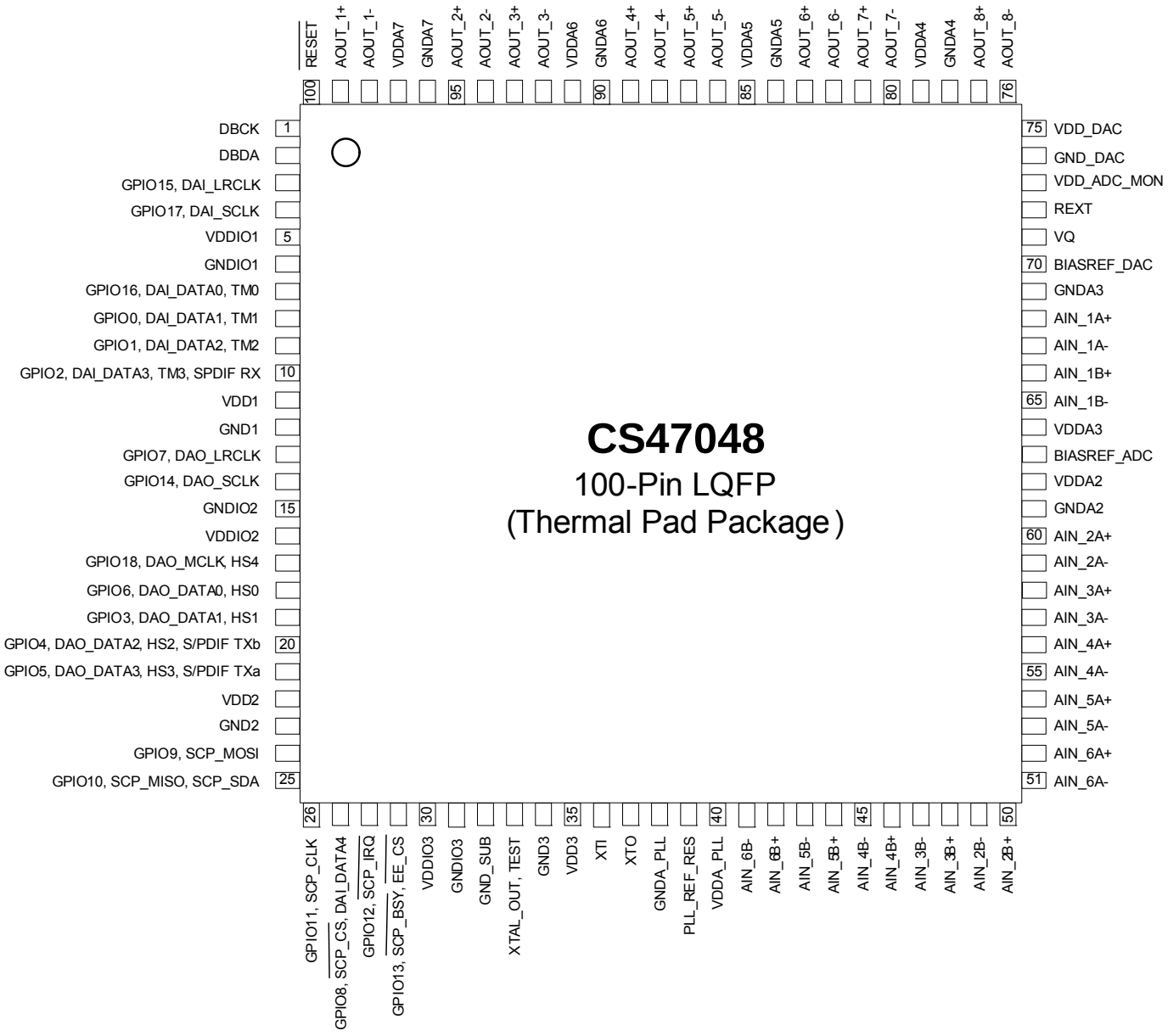


Figure 8-1. CS47048 Pinout Diagram

8.2 CS47028, 100-pin LQFP Pinout Diagram

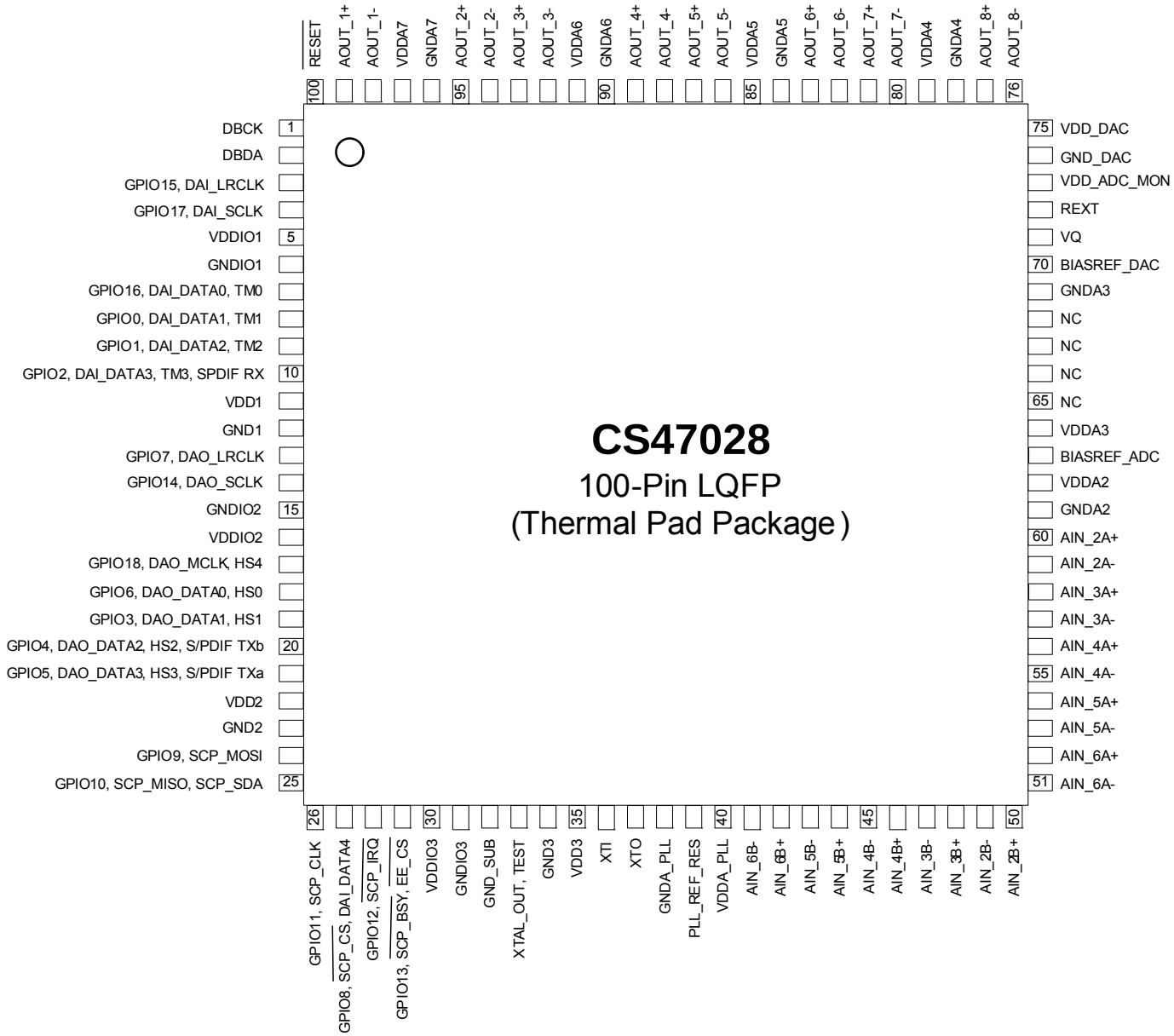


Figure 8-2. CS47028 Pinout Diagram

8.3 CS47024, 100-pin LQFP Pinout Diagram

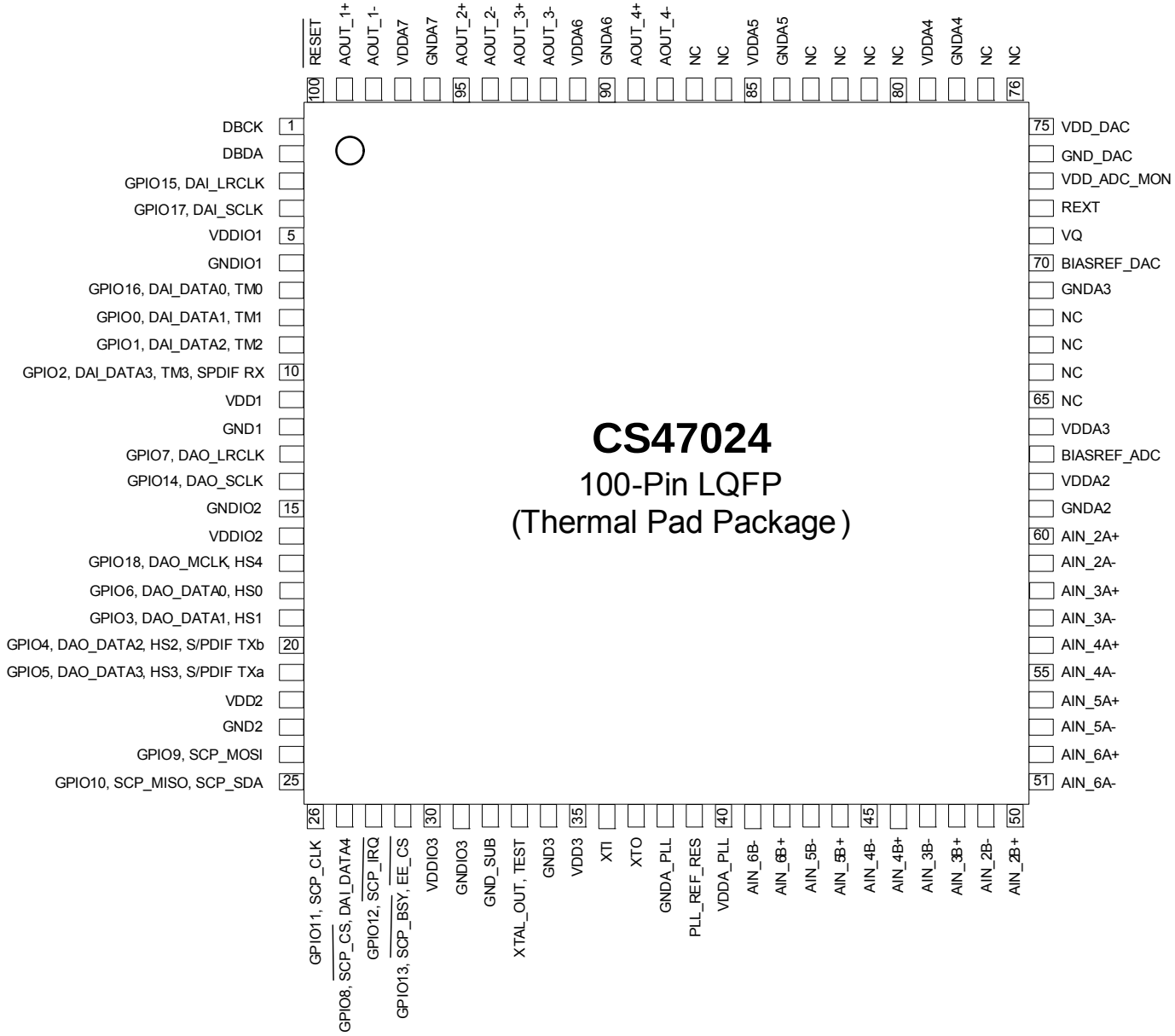
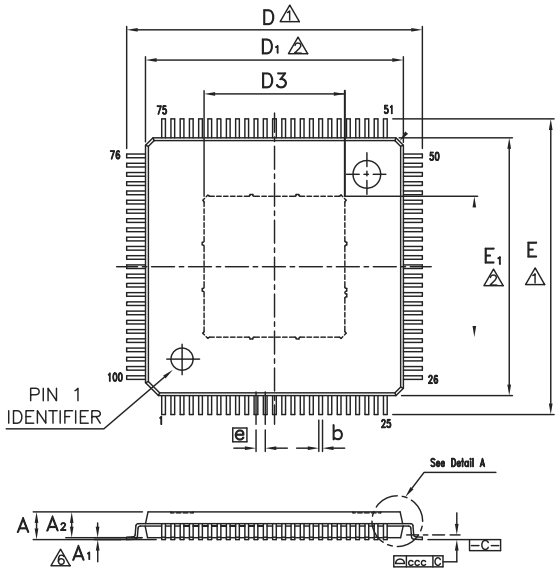
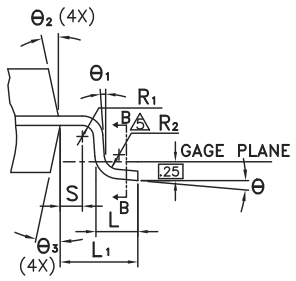


Figure 8-3. CS47024 Pinout Diagram

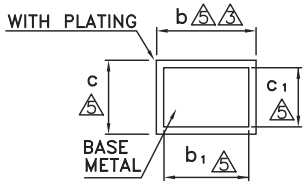
9 100-pin LQFP with Exposed Pad Package Drawing

Fig. 9-1 shows the 100-pin LQFP package with exposed pad for the CS47048, CS47028, and CS47024.





DETAIL A



SECTION B–B

Symbol	Dimension in mm			Dimension in inch		
	Min	Nom	Max	Min	Nom	Max
A	—	—	1.60	—	—	0.063
A1	0.05	—	0.15	0.002	—	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
b	0.17	0.22	0.27	0.007	0.009	0.011
b1	0.17	0.20	0.23	0.007	0.008	0.009
c	0.09	—	0.20	0.004	—	0.008
c1	0.09	—	0.16	0.004	—	0.006
D	15.85	16.00	16.15	0.624	0.630	0.636
D1	13.90	14.00	14.10	0.547	0.551	0.555
E	15.85	16.00	16.15	0.624	0.630	0.636
E1	13.90	14.00	14.10	0.547	0.551	0.555
e	0.50 BSC			0.020 BSC		
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
R1	0.08	—	—	0.003	—	—
R2	0.08	—	0.20	0.003	—	0.008
S	0.20	—	—	0.008	—	—
θ	0°	3.5°	7°	0°	3.5°	7°
θ1	0°	—	—	0°	—	—
θ2	12°TYP					
θ3						
ccc	0.08			0.003		

NOTE :

1. TO BE DETERMINED AT SEATING PLANE -C- .
2. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
4. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
5. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 mm FROM THE LEAD TIP.
6. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
7. CONTROLLING DIMENSION : MILLIMETER.
8. REFERENCE DOCUMENT : JEDEC MS–026.
9. **SPECIAL CHARACTERISTICS C CLASS: ccc**

Exposed Pad Size		
L/F	Dimension in mm	Dimension in inch
D3/E3	7.62 REF	0.300 REF

100LD E–PAD LQFP (14x14x1.4mm) PACKAGE OUTLINE
–Cu L/F,FOOTPRINT 2.0mm

Figure 9-1. 100-pin LQFP Package Drawing

10 Parameter Definitions

10.1 Dynamic Range

The ratio of the RMS value of the signal to the RMS sum of all other spectral components over the specified bandwidth. Dynamic Range is a signal-to-noise ratio measurement over the specified bandwidth made with a -60 dBFS signal. 60 dB is added to resulting measurement to refer the measurement to full-scale. This technique ensures that the distortion components are below the noise level and do not affect the measurement. This measurement technique has been accepted by the Audio Engineering Society, AES17-1991, and the Electronic Industries Association of Japan, EIAJ CP-307. Expressed in decibels.

10.2 Total Harmonic Distortion + Noise

The ratio of the RMS value of the signal to the RMS sum of all other spectral components over the specified bandwidth (typically 10 Hz–20 kHz), including distortion components. Expressed in decibels. Measured at –1 and –20 dBFS as suggested in AES17-1991 Annex A.

10.3 Frequency Response

A measure of the amplitude response variation from 10 Hz–20 kHz relative to the amplitude response at 1 kHz. Units in decibels.

10.4 Interchannel Isolation

A measure of crosstalk between the left and right channels. Measured for each channel at the converter's output with no signal to the input under test and a full-scale signal applied to the other channel. Units in decibels.

10.5 Interchannel Gain Mismatch

The gain difference between left and right channels. Units in decibels.

10.6 Gain Error

The deviation from the nominal full-scale analog output for a full-scale digital input.

10.7 Gain Drift

The change in gain value with temperature. Units in ppm/°C.